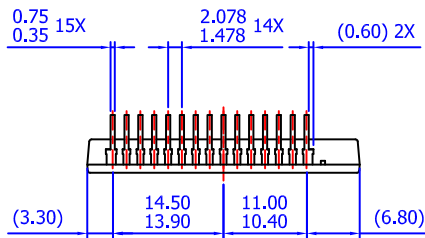
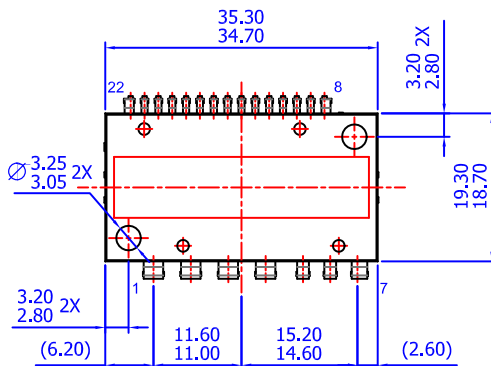


SPMAA-A22 / 22LD, PDD STD, SPM22, CERAMIC, DIP TYPE
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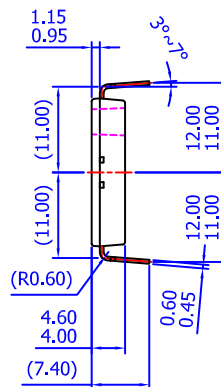
DATE 31 JAN 2017



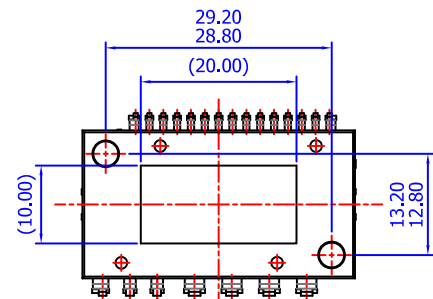
REAR VIEW



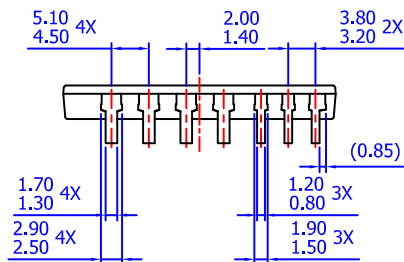
TOP VIEW



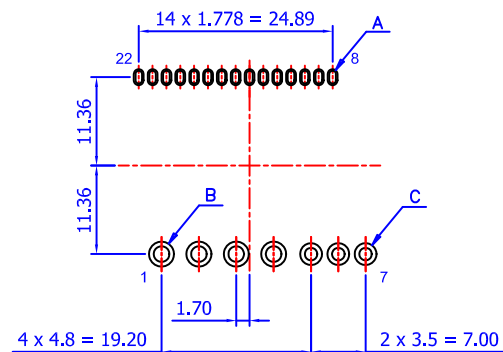
SIDE VIEW



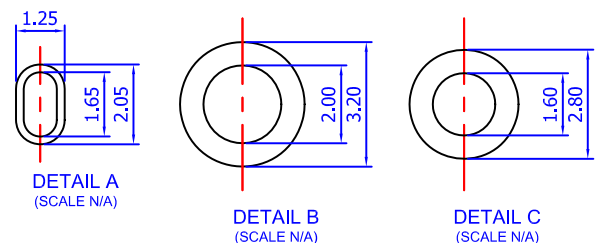
BOTTOM VIEW



FRONT VIEW



- NOTES: UNLESS OTHERWISE SPECIFIED
A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
B) ALL DIMENSIONS ARE IN MILLIMETERS
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
D) () IS REFERENCE
E) [] IS ASS'Y QUALITY



LAND PATTERN RECOMMENDATIONS

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